

Title (en)

METHOD FOR PRODUCING SOLDERABLE AND FUNCTIONAL SURFACES ON CIRCUIT CARRIERS

Title (de)

VERFAHREN ZUM ERZEUGEN VON LÖTFÄHIGEN UND FUNKTIONELLEN OBERFLÄCHEN AUF SCHALTUNGSTRÄGERN

Title (fr)

PROCEDE POUR REALISER DES SURFACES APTES AU BRASAGE ET FONCTIONNELLES SUR DES SUPPORT DE CIRCUITS

Publication

EP 1163827 A1 20011219 (DE)

Application

EP 01927633 A 20010328

Priority

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Abstract (en)

[origin: WO0176334A1] The inventive method provides solderable areas in addition to bondable areas on circuit carriers, wherein solderability is not impaired by exposing the circuit carriers to the effects of temperature. The inventive method comprises the following steps: solderable surfaces are produced by deposition of a solderable metal layer (5), the solder areas are covered by a mask (6), functional surfaces (7, 8) are created in the functional areas and the covering mask (6) is finally removed.

IPC 1-7

H05K 3/24

IPC 8 full level

H05K 3/24 (2006.01)

CPC (source: EP KR US)

H05K 3/02 (2013.01 - KR); **H05K 3/243** (2013.01 - EP US); **H05K 2201/0391** (2013.01 - EP US); **H05K 2203/0361** (2013.01 - EP US); **Y10T 29/49144** (2015.01 - EP US)

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